



## Automotive power Schottky rectifier

Datasheet – production data

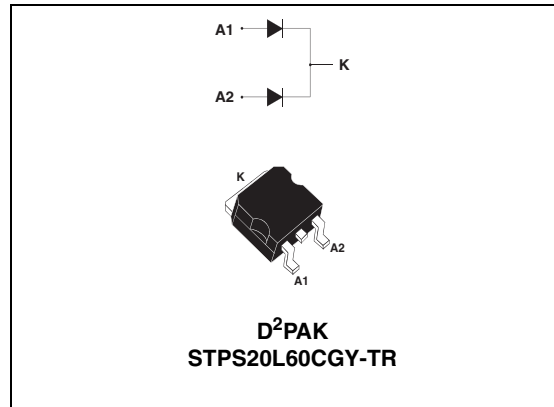
### Features

- Low forward voltage drop
- Negligible switching losses
- Low thermal resistance
- Avalanche capability specified
- AEC-Q101 qualified

### Description

This dual center tap Schottky rectifier is suited for switched mode power supplies and high frequency DC to DC converters.

Packaged in D<sup>2</sup>PAK, this device is intended for use in high frequency inverters for automotive applications.



**Table 1. Device summary**

$I_{F(AV)}$	2 x 10 A
$V_{RRM}$	60 V
$T_j(max)$	150 °C
$V_F(max)$	0.56 V

# 1 Characteristics

**Table 2. Absolute ratings (limiting values, per diode)**

Symbol	Parameter		Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage		60	V
I <sub>F(RMS)</sub>	Forward rms current		30	A
I <sub>F(AV)</sub>	Average forward current	T <sub>C</sub> = 140 °C δ = 0.5	Per diode 20 Per device	A
I <sub>FSM</sub>	Surge non repetitive forward current		t <sub>p</sub> = 10 ms, sinusoidal	220 A
I <sub>R</sub>	Repetitive peak reverse current		t <sub>p</sub> = 2 μs square, F = 1 kHz	1 A
P <sub>ARM</sub>	Repetitive peak avalanche power		t <sub>p</sub> = 1 μs, T <sub>J</sub> = 25 °C	5800 W
T <sub>stg</sub>	Storage temperature range		-65 to + 175	°C
T <sub>J</sub>	Operating junction temperature range <sup>(1)</sup>		-40 to + 150	°C
dV/dt	Critical rate of rise reverse voltage		10000	V/μs

1.  $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistances**

Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case	Per diode Total	1.6 0.85	°C/W
R <sub>th(c)</sub>	Coupling		0.1	°C/W

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_{j(\text{diode } 1)} = P_{(\text{diode } 1)} \times R_{th(j-c)}(\text{per diode}) + P_{(\text{diode } 2)} \times R_{th(c)}$$

**Table 4. Static electrical characteristics (per diode)**

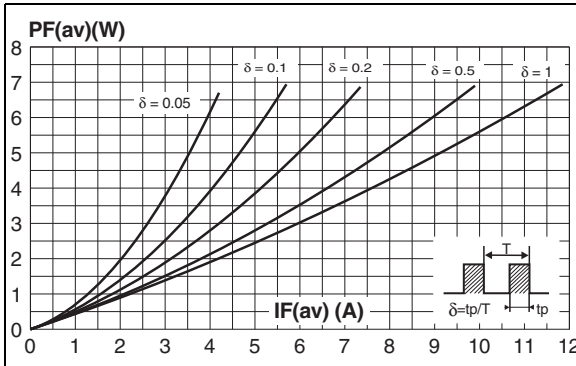
Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>J</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>			350	μA
		T <sub>J</sub> = 125 °C			65	95	mA
V <sub>F</sub> <sup>(1)</sup>	Forward voltage drop	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 10 A			0.6	V
		T <sub>J</sub> = 125 °C	I <sub>F</sub> = 10 A		0.48	0.56	
		T <sub>J</sub> = 25 °C	I <sub>F</sub> = 20 A			0.74	
		T <sub>J</sub> = 125 °C	I <sub>F</sub> = 20 A		0.62	0.7	

1. Pulse test: t<sub>p</sub> = 380 μs, δ < 2%

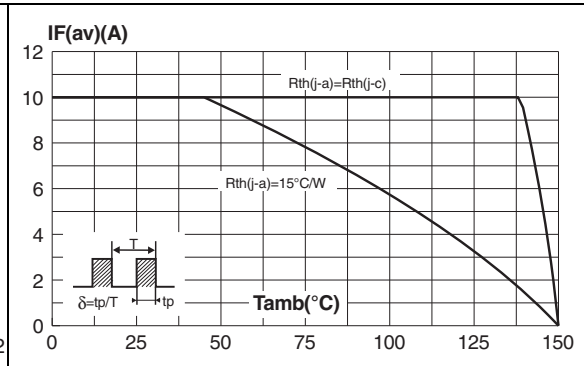
To evaluate the conduction losses use the following equation:

$$P = 0.42 \times I_{F(AV)} + 0.014 \times I_{F(RMS)}^2$$

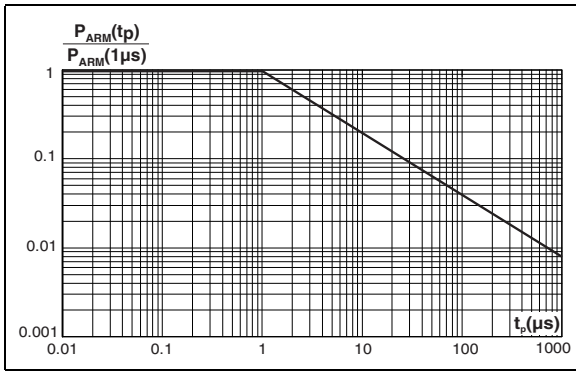
**Figure 1. Average forward power dissipation versus average forward current (per diode)**



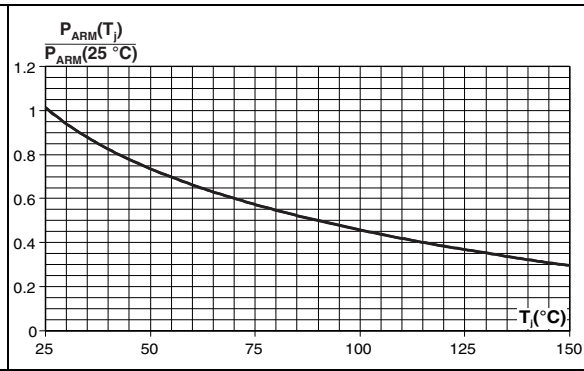
**Figure 2. Average current versus ambient temperature (delta = 0.5) (per diode)**



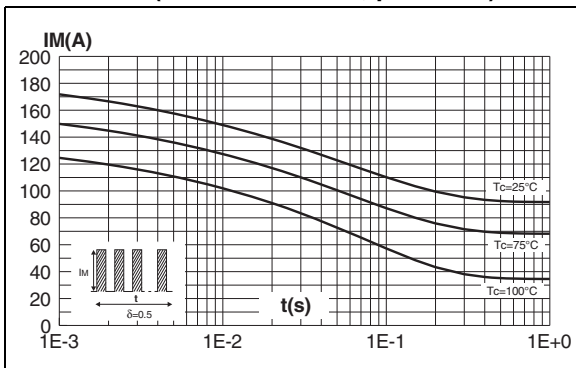
**Figure 3. Normalized avalanche power derating versus pulse duration**



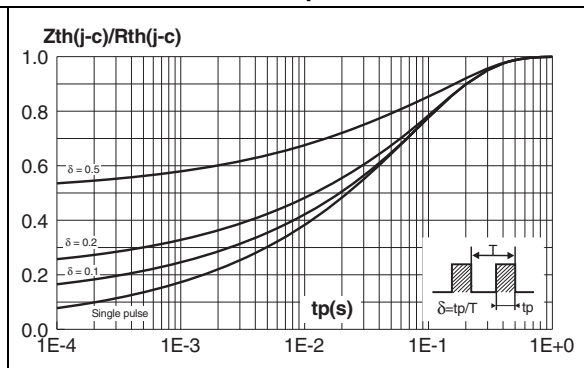
**Figure 4. Normalized avalanche power derating versus junction temperature**



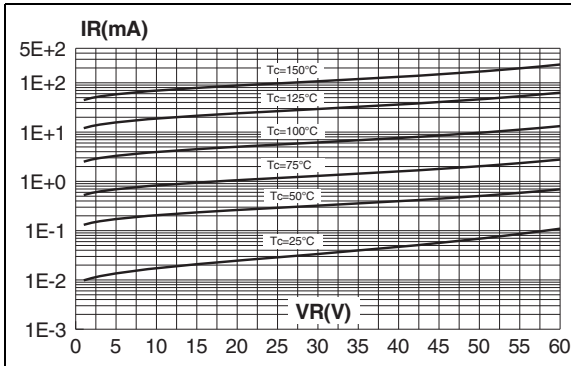
**Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)**



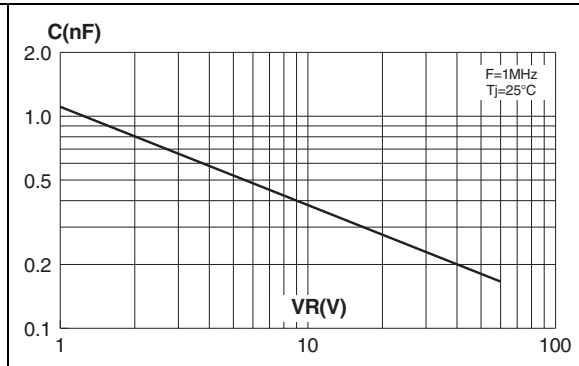
**Figure 6. Relative variation of thermal transient impedance junction to case versus pulse duration**



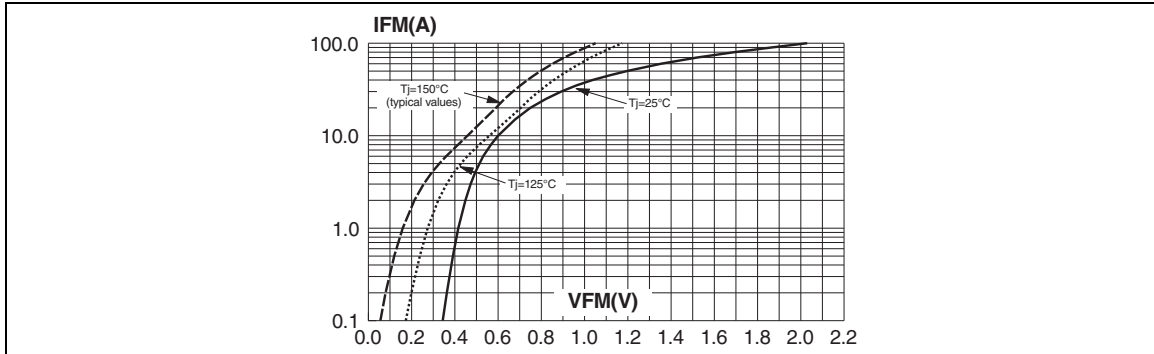
**Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)**



**Figure 8. Junction capacitance versus reverse voltage applied (typical values, per diode)**



**Figure 9. Forward voltage drop versus forward current (maximum values, per diode)**



## 2 Package information

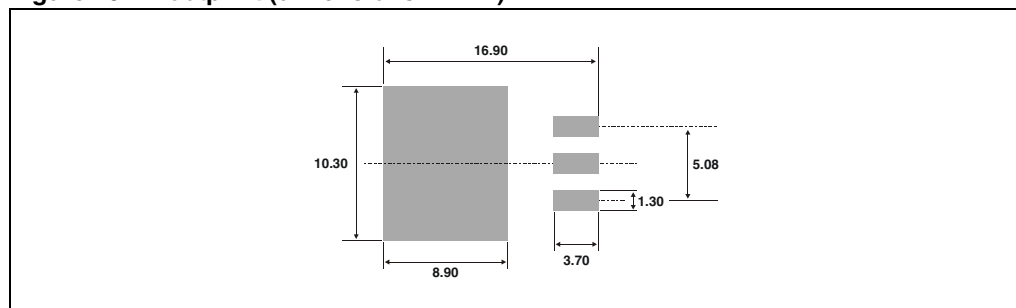
- Epoxy meets UL94, V0
- Cooling method: by conduction (method C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

Table 5. D<sup>2</sup>PAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 10. Footprint (dimensions in mm)



### 3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS20L60CGY-TR	STPS20L60CGY	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel

### 4 Revision history

Table 7. Document revision history

Date	Revision	Changes
24-Oct-2012	1	Initial release.

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